Description

The VSM4N15 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

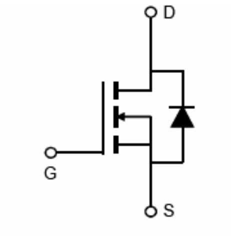
General Features

- V_{DS} = 150V, I_D = 4A
  $R_{DS(ON)}$ < 180mΩ @ V_{GS}=10V (Typ:140mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits

SOT-223



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM4N15-S23	VSM4N15	SOT-223	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	4	A
Drain Current-Pulsed (Note 1)	I_{DM}	16	A
Maximum Power Dissipation	P_D	4	W
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	31	℃/W

Electrical Characteristics (T_A=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	150	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=150V,V_{GS}=0V	-	-	1	μA

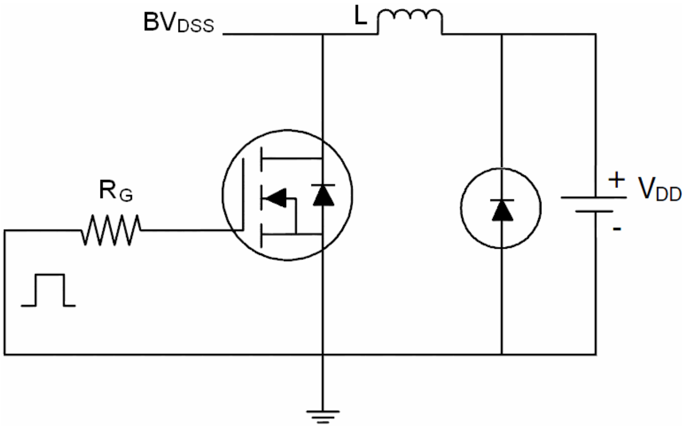
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1.5	2.0	2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=4A	-	140	180	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=4A	-	5	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=25V,V_{GS}=0V, F=1.0MHz	-	900	-	PF
Output Capacitance	C_{oss}		-	115	-	PF
Reverse Transfer Capacitance	C_{rss}		-	70	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=75V, R_L=19Ω V_{GS}=10V,R_G=6Ω	-	8	-	nS
Turn-on Rise Time	t_r		-	10	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	20	-	nS
Turn-Off Fall Time	t_f		-	15	-	nS
Total Gate Charge	Q_g	V_{DS}=75V,I_D=4A, V_{GS}=10V	-	19		nC
Gate-Source Charge	Q_{gs}		-	5.5	-	nC
Gate-Drain Charge	Q_{gd}		-	7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=4A	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	4	A

Notes:

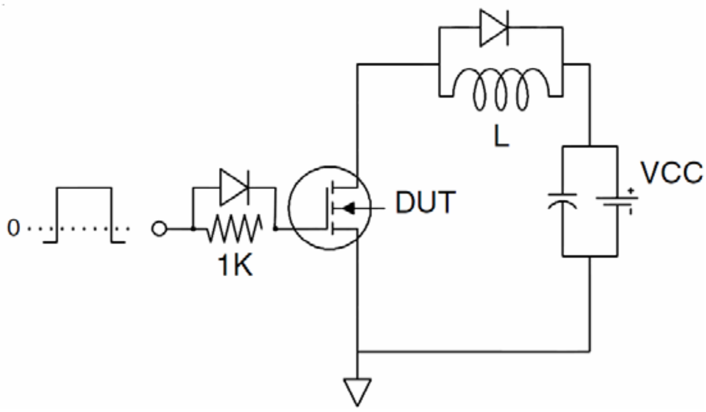
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to product

Test Circuit

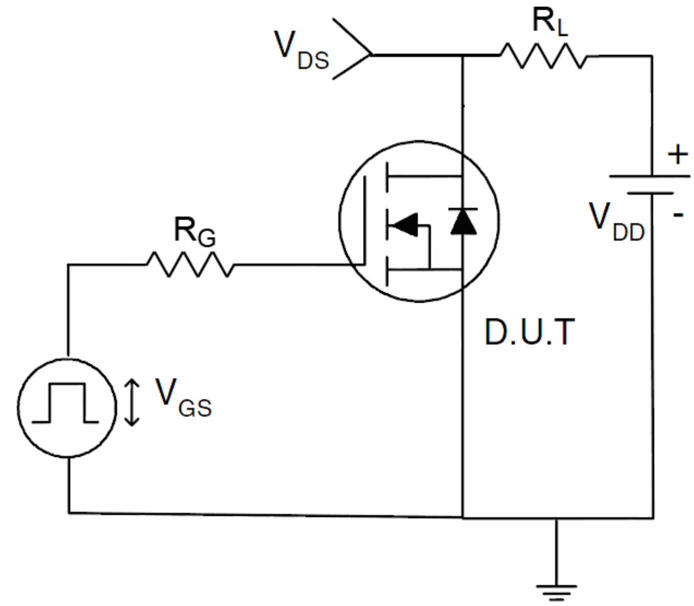
1) E_{AS} Test Circuit



2）Gate Charge Test Circuit



3）Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

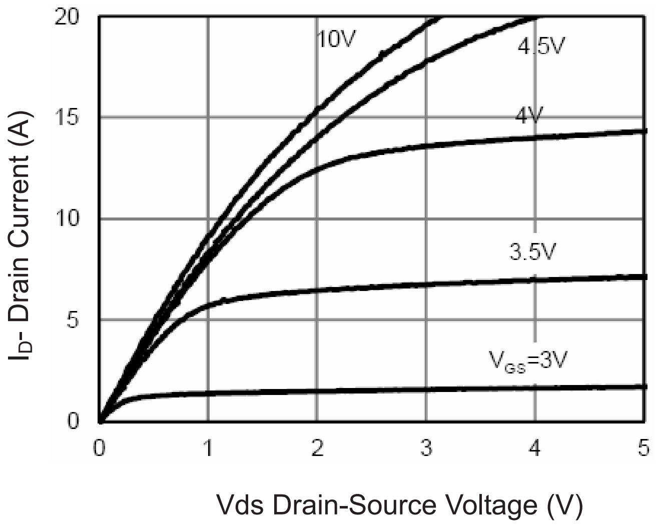


Figure 1 Output Characteristics

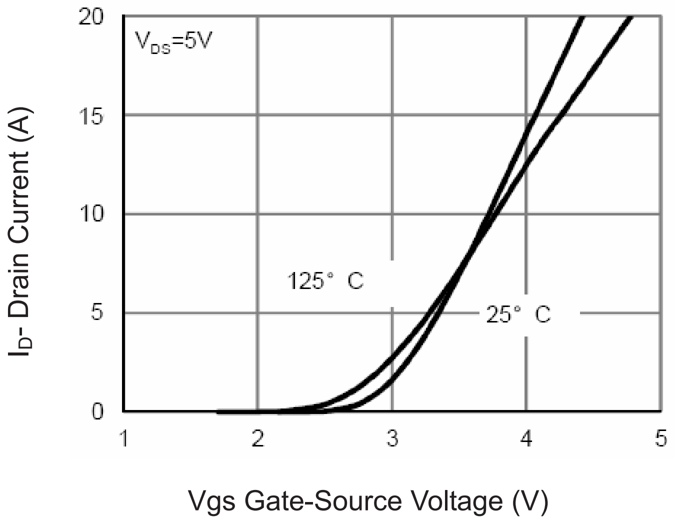


Figure 2 Transfer Characteristics

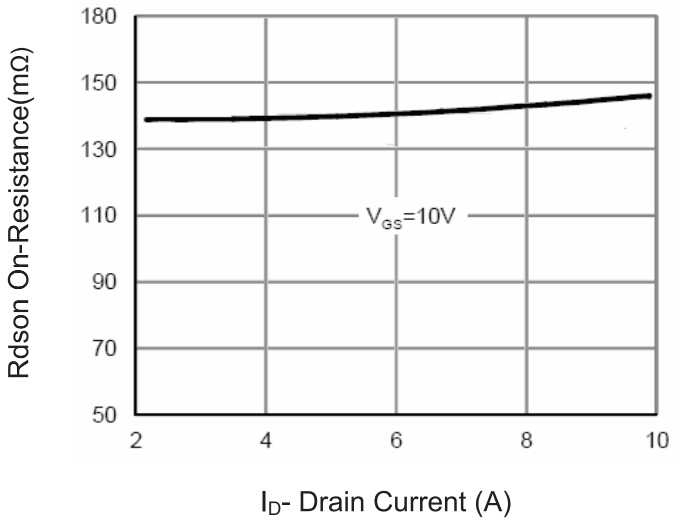


Figure 3 Rdson- Drain Current

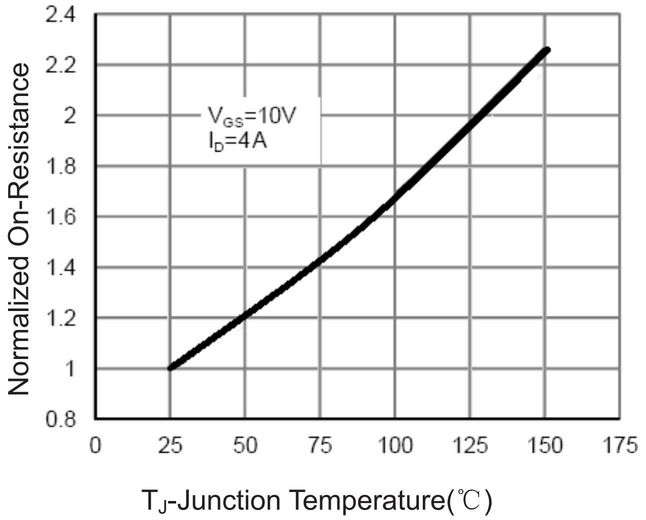


Figure 4 Rdson- Junction Temperature

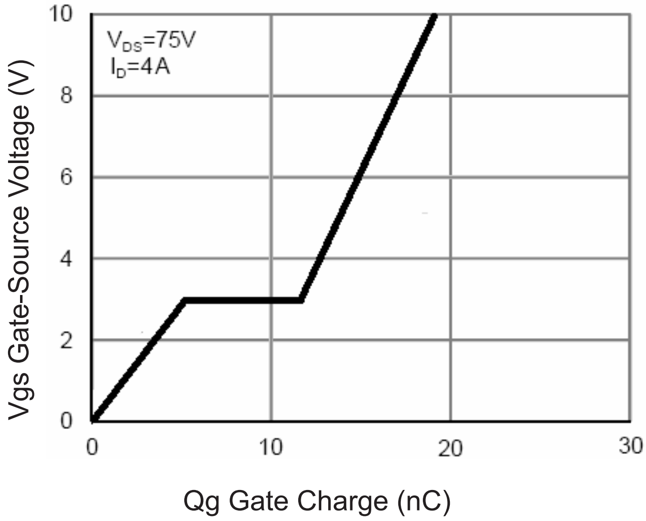


Figure 5 Gate Charge

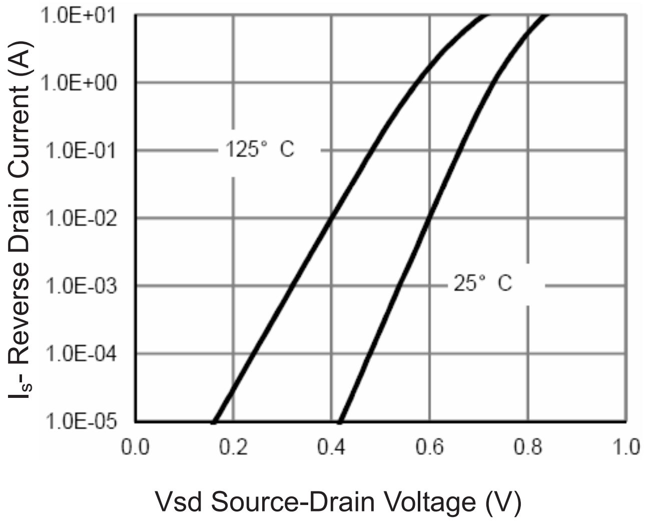


Figure 6 Source- Drain Diode Forward

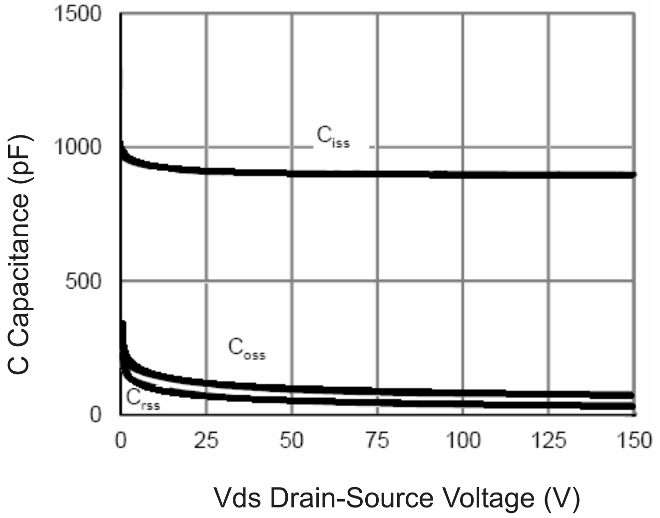


Figure 7 Capacitance vs Vds

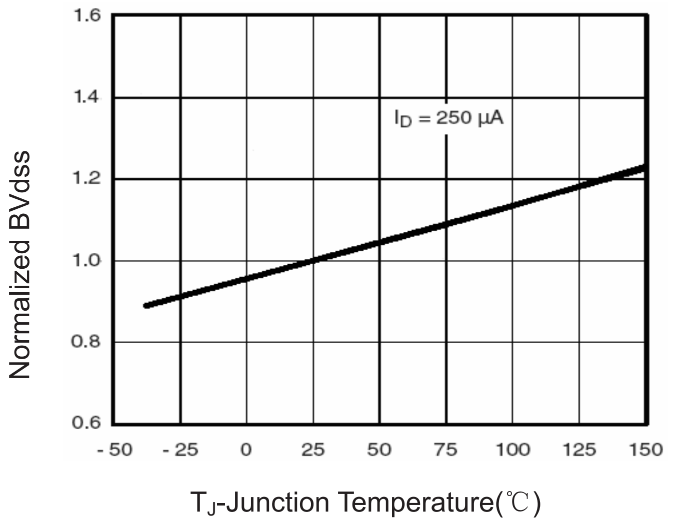


Figure 9 BV_{DSS} vs Junction Temperature

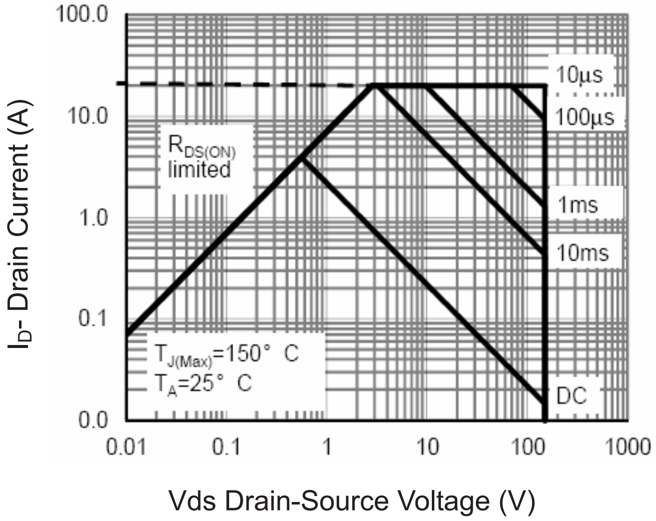


Figure 8 Safe Operation Area

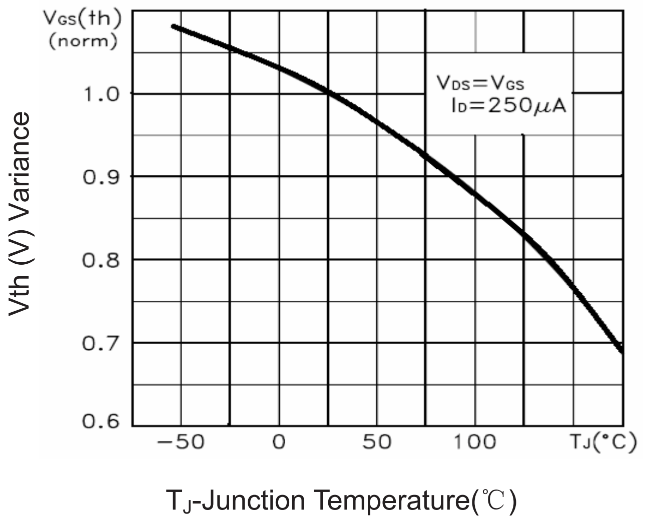


Figure 10 $V_{GS(th)}$ vs Junction Temperature

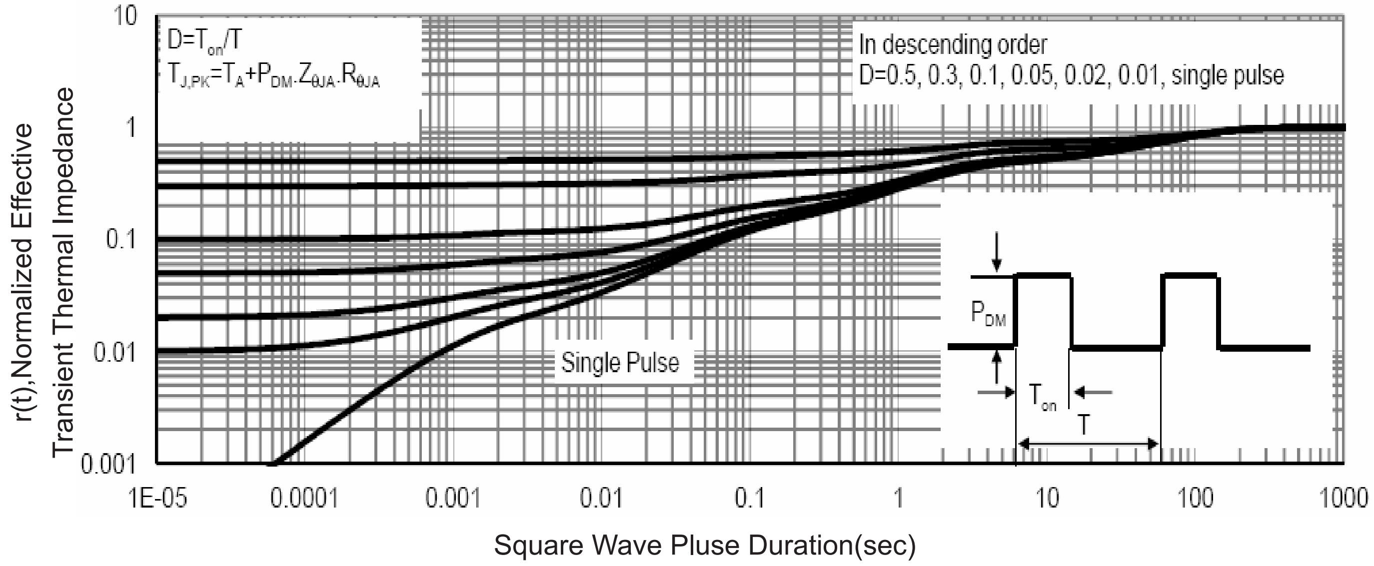
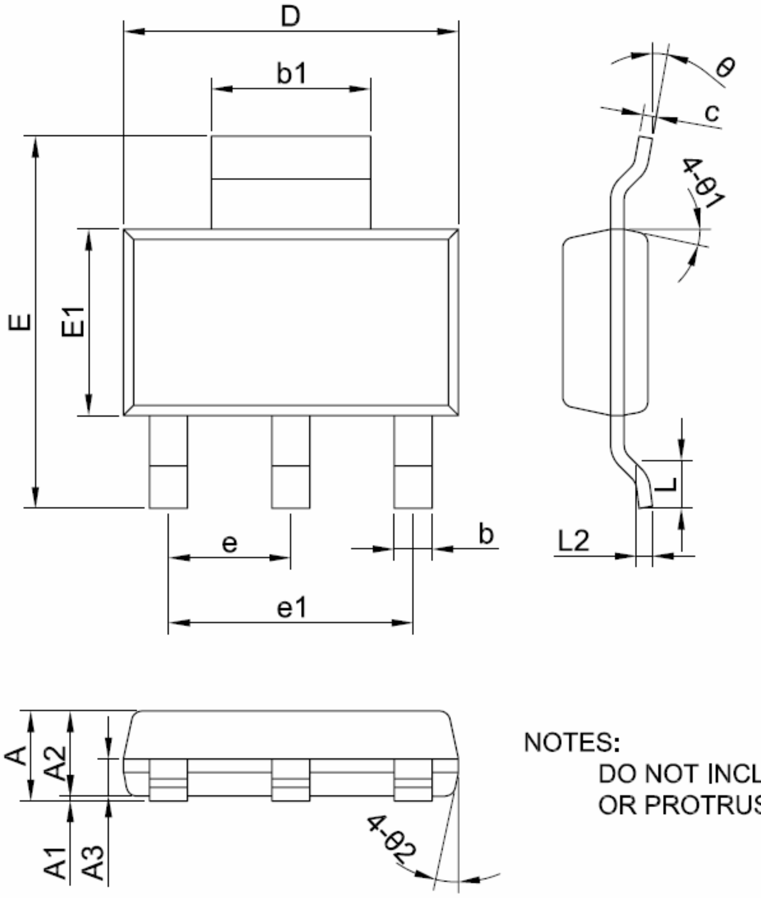


Figure 11 Normalized Maximum Transient Thermal Impedance

SOT-223-3L Package Information

SYMBOL	MIN	NOM	MAX
A	1.55	—	1.80
A1	0.02	—	0.12
A2	1.45	1.60	1.75
A3	0.60	0.70	0.80
b	0.60	—	0.80
b1	2.90	—	3.10
c	0.24	—	0.32
D	6.20	6.30	6.50
E	6.70	7.00	7.30
E1	3.30	3.50	3.70
e	2.299REF		
e1	4.598REF		
L	0.90MIN		
L2	0.30BSC		
θ	0°	—	10°
θ_1	10°	12°	14°
θ_2	10°	12°	14°



NOTES:
DO NOT INCLUDE MOLD FLASH
OR PROTRUSIONS